

Date: 11/20/20

Attendees: Subu, Jinshui, Myron, Nhat, Bill, Phillippe, Reza, Rohit, Sam, Scott, Shreyas, Swami, Tawfik, Bapi, JP, David A, David R, Anu, Archna, DJ, Eelco, Gus, Javi, Rohit, Allan, Kevin, Letizia,

1. Rolling Agenda:

- a. November 13th - no meeting (workshop)
- b. November 20th - Prof. Iyer
- c. November 27th - no meeting
- d. December 4th -
- e. December 11th - Breakout conversation on Ali's reference architecture
- f. December 18th - Business workgroup proposal
- g. January 8th -

2. Agenda

- a. Business work group
 - i. <https://docs.google.com/spreadsheets/d/1j8IGDbPCdONFzZNGyveIXFKZjkmMkVWQym1JS7DoCXo/edit?usp=sharing> - Link for Business Role Play Sign Up
- b. Prof. Iyer, UCLA
 - i. Excellent intro to CHIPS program
- c. Wiki, white paper update

3. Opens

- a.

4. Weekly workstream minutes

- a. BoW - <https://github.com/opencomputeproject/ODSA-BoW/issues/38>:
 - i. Completed definitions for all the components in the cross-PHY sheet.
 - ii. BoW spec 1.0 - good progress towards an end of September
- b. CDX -
https://docs.google.com/document/d/1ZVA1_qMWSdIhjHBF21pwucmy9LqAID8f_Qwpog8VcxI/edit?usp=sharing
- c. Link Layer -
https://docs.google.com/document/d/1vlbfsgkG4ef8Sqs1IBb1_tvlljl-ffJS0T8-PnESxTk/edit?usp=sharing
 - i. Requirements done
 - ii. First rev discussion on DiPort
- d. PIPE -
https://docs.google.com/document/d/1g9m6FdBaWzHj8BIRI5ADlBjVT-GR_8ODVaxHTg5Snw0/edit?usp=sharing
 - i. Aiming for final clean up. Going to publish as a white paper
- e. PoC HW
<https://docs.google.com/document/d/1UOdbOrF2TG7zZQCadLFZ1ujljAkl3FXra5wGJ-QkZ1o/edit?usp=sharing>
 - i. Board design complete, released for fab

- ii. ~~Targeting November workshop for a demo~~
 - f. PoC SW -
 - <https://docs.google.com/document/d/1kpgZL1mH-sMOdA0wWFOcnNLoctSZdo68jw-UEVcqLZo/edit?usp=sharing>
 - i. Working on remote access
 - g. Open HBI - contact Kenneth Ma
 - h. Business workflow
 - i. open MIC 8/28, follow up today
- 5. Speaker ideas
 - a. Quality and Reliability - ESD, aging, electromigration - Bill HIR workgroup, ANSYS, packaging reliability - thermal effects, mechanical - as applies to chiplets
 - b. Anyone making chiplets - commercial talks focused on chiplets
 - i. ~~Classes of chiplets we anticipate in the coming years (University - UCLA? - Ali will check, IBM)~~
 - c. Memory access discussion - HBM, GenZ, OMI - how do they become compatible with chiplets - WD/Micron/IBM/Samsung/SK/Seagate - new protocol? Sequence of memory-focused talks - Allan - October
 - d. Prof. Flynn
 - e. DARPA official CHIPS - Eelco - October/November
 - f. CHIPS - Andreas - October
 - g. TSMC - Bill, Suresh
 - h. Transaction Protocol for D2D review
 - i. Bit errors in substrates
 - j. End user workgroup - DJ
 - k. AIB by Dave
 - l. Any other foundry (Global) or AMAT?
 - m. David Allen on memory